

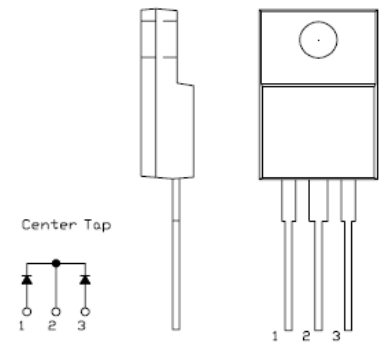
MBRF30150CT SCHOTTKY RECTIFIER

Applications:

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

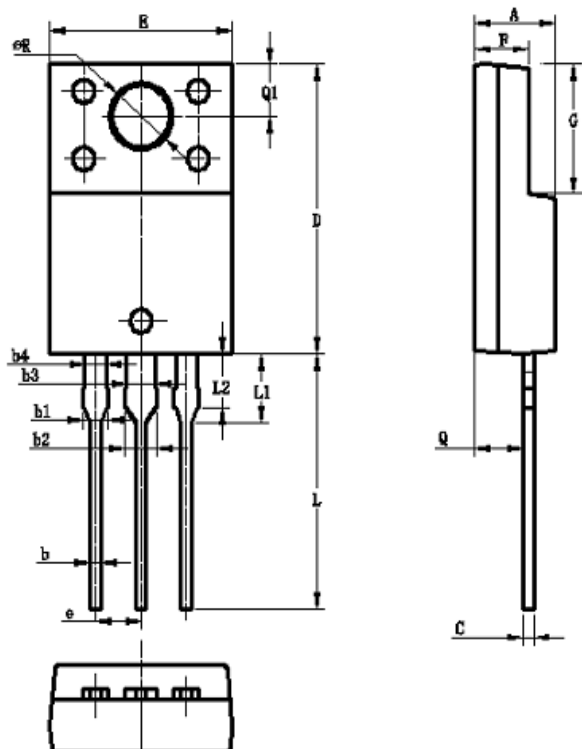
Features:

- 150°C T_J operation
- Center tap configuration
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb - Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

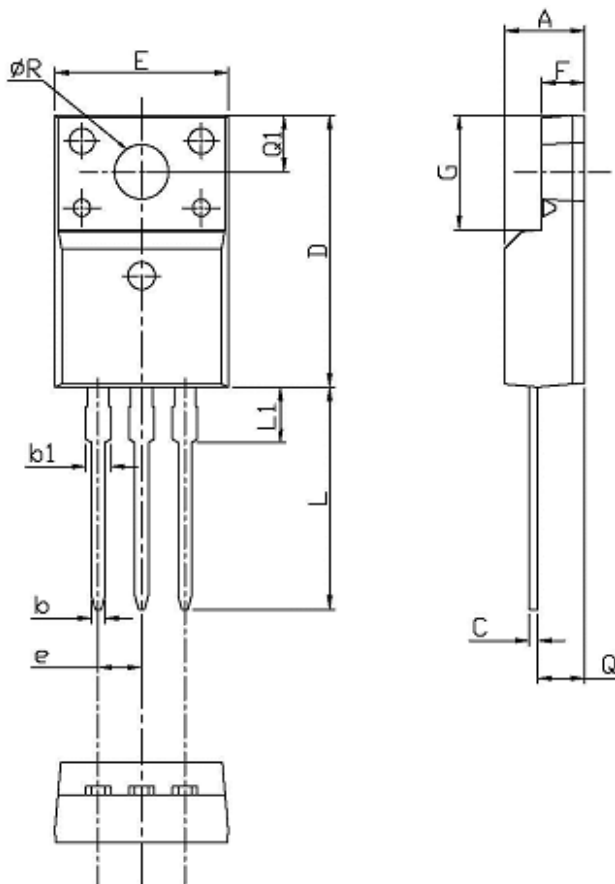


OUTLINE DRAWING

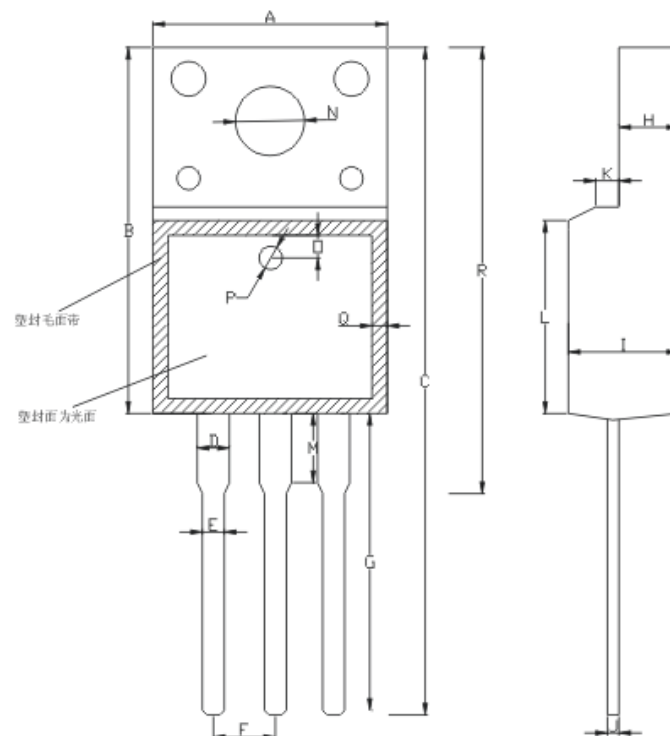
Mechanical Dimensions: In mm / Inches



	OPTION 1		OPTION 2	
Dim	Min	Max	Min	Max
A	4.4	4.6	4.30	4.70
b	0.6TYP		0.50	0.75
b1	1.3TYP		1.30	1.40
b2	1.7TYP		1.70	1.80
b3	1.6TYP		1.50	1.75
b4	1.2TYP		1.10	1.35
C	0.60TYP		0.50	0.75
D	14.8	15.1	14.80	15.20
E	10.06	10.26	9.96	10.36
e	2.55TYP		2.54TYP	
F	2.9	3.1	2.80	3.20
G	6.5	6.9	6.50	6.90
L	12.7	13.7	13.2	12.8
L1	3.4	3.8	3.60	4.00
L2	2.6	3.0	-	-
Q	2.5	2.9	2.50	2.90
Q1	2.5	2.9	2.70REF	
ØR	3.5REF		3.50REF	



Dim	OPTION 3		OPTION 4	
	Min	Max	Min	Max
A	4.53	4.93	4.50	4.90
b	0.71	0.91	0.70	0.90
b1	1.15	1.39	1.33	1.47
C	0.36	0.53	0.45	0.60
D	15.67	16.07	15.67	16.07
E	9.96	10.36	9.96	10.36
e	2.54TYP		2.54 BSC	
F	2.34	2.76	2.34	2.74
G	6.50	6.90	6.48	6.88
L	12.37	12.77	12.78	13.18
L1	2.23	2.63	3.03	3.43
Q	2.56	2.96	2.56	2.96
Q1	3.10	3.50	3.10	3.50
ϕR	2.98	3.38	3.08	3.28



A:10.20 ± 0.50	B:15.90 ± 0.50	C:29.00 ± 1.00	D:1.24 ± 0.10
E:0.80 ± 0.10	F:2.54 ± 0.10	G:13.10 ± 1.0	H:2.55 ± 0.05
I:4.70 ± 0.05	J:0.50 ± 0.05	K:1.20 ± 0.20	L:8.00 ± 0.50
M:3.00 ± 0.50	N:3.20 ± 0.20	O:1.25 ± 0.05	P:1.5 ± 0.05
Q:1.0 ± 0.20	R:19.2 ± 1.0		

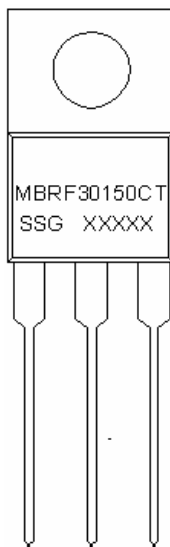
OPTION 5(SR)

ITO-220AB

Technical Data
Data Sheet N0854, Rev. -

Green Products

Marking Diagram:



Where XXXXX is YYWWL

MBR = Device Type
F = Package type
30 = Forward Current (30A)
150 = Reverse Voltage (150V)
CT = Configuration
SSG = SSG
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Ordering Information:

Device	Package	Shipping
MBRF30150CT	ITO-220AB (Pb-Free)	50pcs / tube

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	V_{RWM}	-	150	V
Average Forward Current	$I_{F(AV)}$	50% duty cycle @ $T_C = 133^\circ\text{C}$, rectangular wave form	30	A
Peak Repetitive Forward Current(per leg)	I_{FRM}	Rated V_R square wave, 20KHz $T_C = 133^\circ\text{C}$	20	A
Peak One Cycle Non-Repetitive Surge Current (per leg)	I_{FSM}	8.3 ms, half Sine pulse	150	A

Electrical Characteristics:

Characteristics	Symbol	Condition	Max.	Units
Forward Voltage Drop (per leg) *	V_{F1}	@ 15 A, Pulse, $T_J = 25\text{ }^{\circ}\text{C}$	1.00	V
	V_{F2}	@ 15 A, Pulse, $T_J = 125\text{ }^{\circ}\text{C}$	0.80	V
Reverse Current (per leg) *	I_{R1}	@ $V_R = \text{rated } V_R$ $T_J = 25\text{ }^{\circ}\text{C}$	1.0	mA
	I_{R2}	@ $V_R = \text{rated } V_R$ $T_J = 125\text{ }^{\circ}\text{C}$	6.0	mA
Junction Capacitance (per leg)	C_T	@ $V_R = 5\text{ V}$, $T_C = 25\text{ }^{\circ}\text{C}$ $f_{SIG} = 1\text{ MHz}$	400	pF
Typical Series Inductance (per leg)	L_S	Measured lead to lead 5 mm from package body	8.0	nH
Voltage Rate of Change	dv/dt	-	10,000	V/ μs

* Pulse Width < 300 μs , Duty Cycle <2%

Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T_J	-	-55 to +150	$^{\circ}\text{C}$
Storage Temperature	T_{stg}	-	-55 to +150	$^{\circ}\text{C}$
Maximum Thermal Resistance Junction to Case	$R_{\theta JC}$	DC operation	2.0	$^{\circ}\text{C/W}$
Maximum Thermal Resistance, Case to Heat Sink	$R_{\theta JA}$	DC operation	60	$^{\circ}\text{C/W}$
Maximum Thermal Resistance, Case to Heat Sink	$R_{\theta CS}$	Mounting surface, smooth and greased	0.50	$^{\circ}\text{C/W}$
Approximate Weight	wt	-	2	g
Case Style	ITO-220AB			

Figure 1
Typical Forward Characteristics

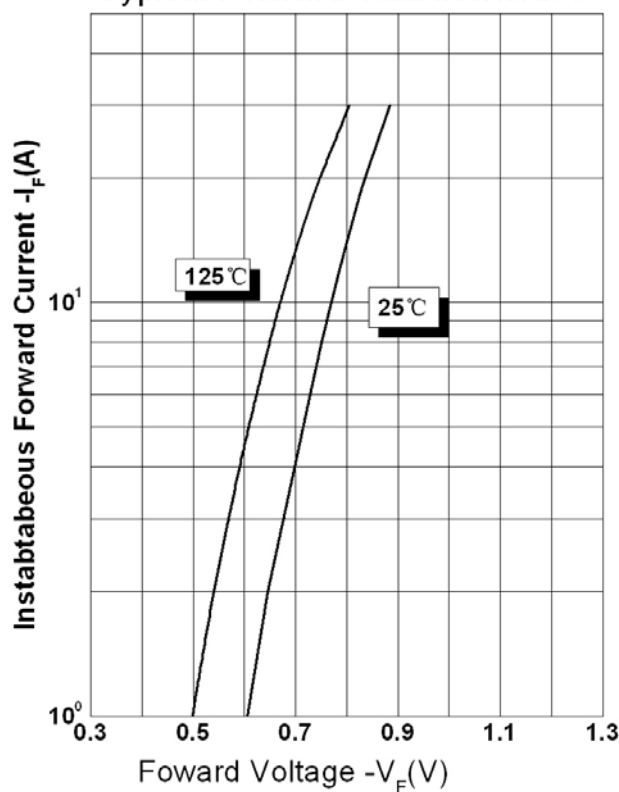


Figure 2
Typical Reverse Characteristics

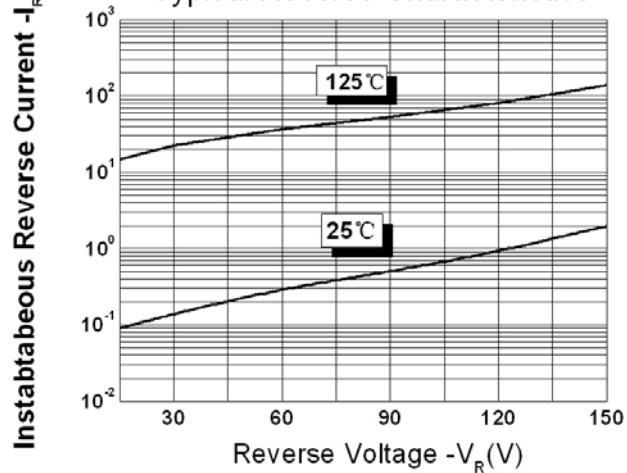
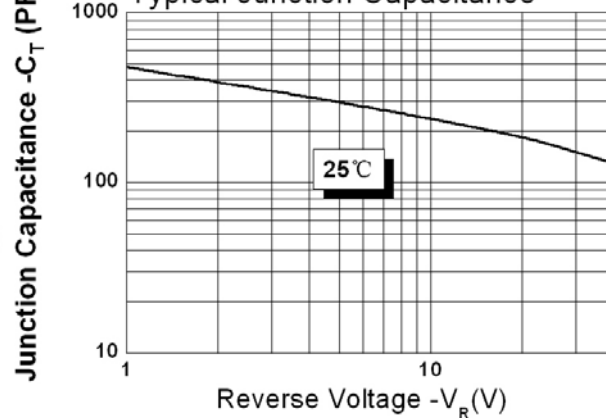


Figure 3
Typical Junction Capacitance



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